



Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-13. **(Cancelled)**

14. **(Previously Presented)** The method of claim 16 wherein the bath comprises at least one additional silane coupling agent, namely, a chloro-silane coupling agent and the boric acid is present in the range from about 0.1% to 5% of the combined weight of said coupling agents.

15. **(Cancelled)**

16. **(Currently Amended)** The method of claim ~~13~~ 28 wherein said weak acid is boric acid.

17-22. **(Cancelled)**

23. **(Currently Amended)** In the method of making an epoxy resin article reinforced by multifilament, fiberglass fabric, the improvement which comprises the steps of providing a latent catalyst inhibitor on the surfaces of the filaments of the fiberglass fabric and allowing epoxy resin to flow into the capillaries formed by fiber filaments thereby substantially reducing the number of voids in the space between filaments in the article as compared to an article prepared without said inhibitor on filament surfaces.

24-26. **(Cancelled)**

27. **(Currently Amended)** The epoxy resin article of claim ~~26~~ 23 wherein the article is a circuit board.

28. **(New)** A method of finishing a glass fabric that is used for reinforcing an epoxy resin article comprising the steps of:

- a) providing fabric woven from glass fiber;
- b) cleaning said fabric to remove sizing and other deposits on the surface of the filaments in the glass fiber;
- c) preparing a bath for said fabric comprising water and at least one cationic amino-silane coupling agent.
- d) immersing said cleaned fabric in said bath;
- e) removing the fabric from the bath and removing excess bath solution;
- f) drying the fabric;
- g) immersing the finish and dried fabric in a solution of a weak acid; for complexing the amino function of said agent; and,
- h) drying the fabric whereby said fabric when used to reinforce an epoxy article will produce an article with substantially reduced voids.